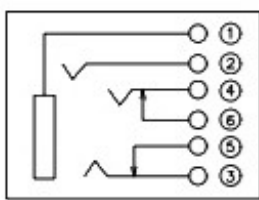
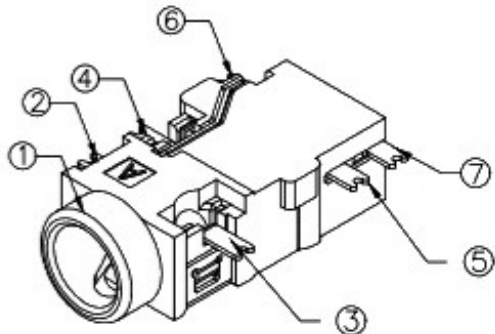


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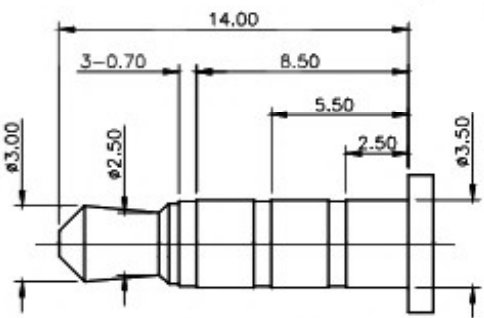
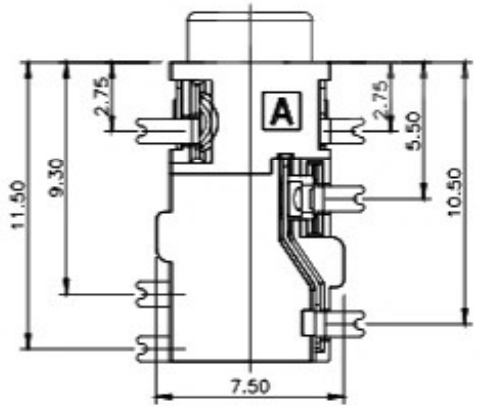
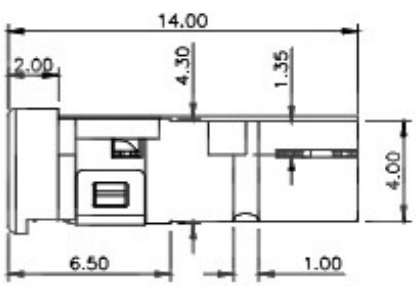
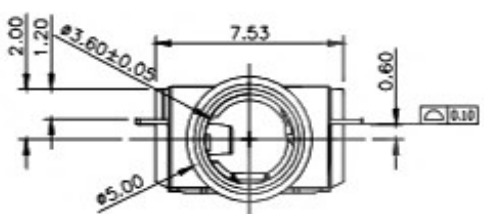
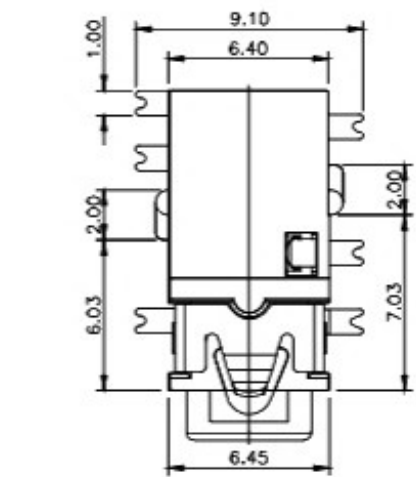
1. REQUEST OF THE SPECIFICATION:
  - 1.1 CONTACT CURRENT RATING: 1A;
  - 1.2 CONTACT RESISTANCE: 100 mΩ MAX.;
  - 1.3 INSULATION RESISTANCE: 100MΩ MIN.;
  - 1.4 DIELECTRIC WITHSTANDING: 500V AC MIN.;
  - 1.5 DURABILITY: 5,000 CYCLES MIN.;
  - 1.6 CONNECTOR MATING FORCES: 29.8N (3.00Kgf) MAX.;
  - 1.7 CONNECTOR UNMATING FORCES: 2.98N(0.30Kgf) MIN.;



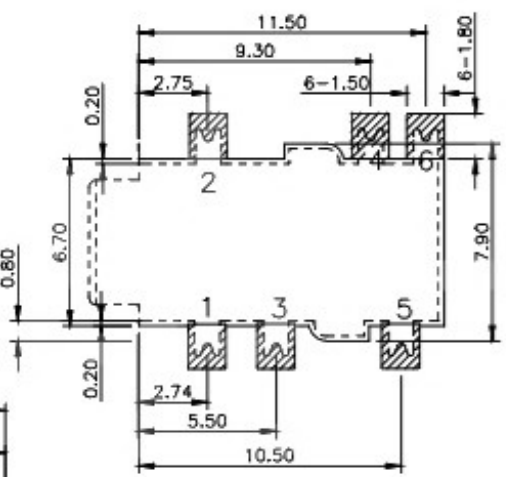
SCHEMATIC



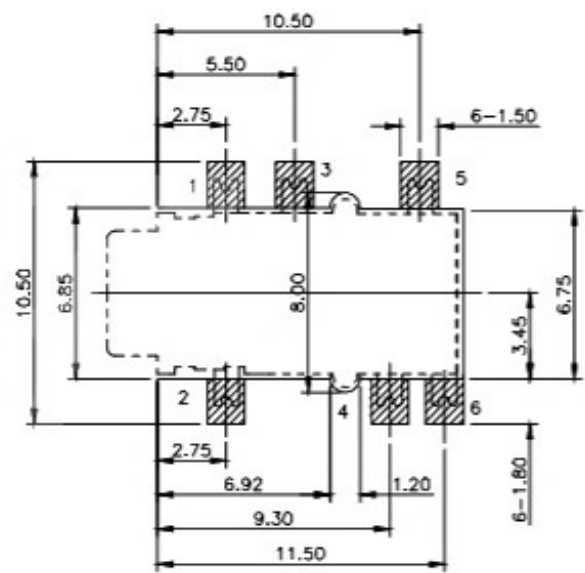
3D VIEW



( $\phi 3.50$ mm 4 POLE PLUG DETAIL DRAWING)



正贴 P.C.B. LAYOUT TOP VIEW



反贴 P.C.B. LAYOUT TOP VIEW

ITEM	NAME	QTY	DESCRIPTION	NOTE
7	TERMINAL #7	1	PHOSPHOR BRONZE; NICKEL(40%MIN.) UNDER PLATING OVERALL;GOLD FLASH ON SOLDER AREA	T=0.20
6	TERMINAL #6	1	PHOSPHOR BRONZE; NICKEL(40%MIN.) UNDER PLATING OVERALL;GOLD FLASH ON SOLDER AREA	T=0.20
5	TERMINAL #5	1	SUS304; THE BOTTOM OF THE NICKEL(40%MIN.); THE WHOLE GOLD FLASH PLATING.	T=0.20
4	TERMINAL #4	1	SUS304; NICKEL(40%MIN.) UNDER PLATING OVERALL;GOLD FLASH ON CONTACT AREA	T=0.20
3	TERMINAL #3	1	PHOSPHOR BRONZE; NICKEL(40%MIN.) UNDER PLATING OVERALL;GOLD FLASH ON SOLDER AREA GOLD FLASH ON CONTACT AREA	T=0.20
2	TERMINAL #2	1	SUS304; THE BOTTOM OF THE NICKEL(40%MIN.); THE WHOLE GOLD FLASH PLATING.	T=0.20
1	HOUSING	1	PPA COLOR BLACK	



东莞市溪榜电子有限公司

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PART NAME	PHONE JACK (SMD)		DRAWING	Y.C.Zhang	DWG.No.	
PART NO.	PJ-399E		CHECK	G.C.Chen	REV.	A1
UNIT :	TOLERANCE	UP TO 5	APPROVAL		DATE	
mm	OTHERWISE	ABOVE 5 ~30	SCALE	4:1	PAGE	1 OF 1
		ABOVE 30				
		ANGLE				
		±0.2				
		±0.3				
		±0.5				
		±3				
		0°±3'				